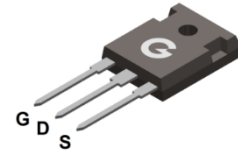
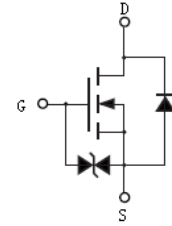


### Features

- Low  $R_{DS(ON)}$
- Fast switching
- Low gate charge
- Low Reverse transfer capacitances

HF



TO-247

### Mechanical Data

- Case: TO-247
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matted-Tin plated; Solderable Per MIL-STD-202, Method 208

### Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL9N90KU	TO-247	30 pcs / Tube	9N90KU

### Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	900	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current ( $T_C = 25^\circ\text{C}$ )	$I_D$	9	A
Continuous Drain Current ( $T_C = 100^\circ\text{C}$ )	$I_D$	5.7	A
Pulsed Drain Current ( $t_p = 10\mu\text{s}$ , $T_C = 25^\circ\text{C}$ )	$I_{DM}$	36	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	500	mJ
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	250	W
Operating Junction Temperature Range	$T_J$	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	-	0.5	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	-	-	40	$^\circ\text{C/W}$

### Electrical Characteristics (@ T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
V <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	900	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 900V, V <sub>GS</sub> = 0V	-	-	25	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±10	μA
<b>On Characteristics</b>						
R <sub>DS(ON)</sub>	Drain-Source On-resistance *1	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.5A	-	-	1.1	Ω
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2	-	4	V
<b>Dynamic Characteristics</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>GS</sub> = 0V	-	2716	-	pF
C <sub>OSS</sub>	Output Capacitance	V <sub>DS</sub> = 25V	-	211	-	
C <sub>RSS</sub>	Reverse Transfer Capacitance	f = 1MHz	-	11	-	
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time *3	V <sub>DD</sub> = 450V I <sub>D</sub> = 9A R <sub>G</sub> = 10Ω	-	30.4	-	ns
t <sub>r</sub>	Turn-on Rise Time *3		-	41.6	-	
t <sub>d(OFF)</sub>	Turn-Off Delay Time *3		-	82	-	
t <sub>f</sub>	Turn-Off Fall Time *3		-	52	-	
Q <sub>G</sub>	Total Gate-Charge	V <sub>DD</sub> = 720V	-	58	-	nC
Q <sub>GS</sub>	Gate to Source Charge	V <sub>GS</sub> = 10V	-	10.6	-	
Q <sub>GD</sub>	Gate to Drain (Miller) Charge	I <sub>D</sub> = 9A	-	23.4	-	
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage *1	I <sub>SD</sub> = 9A, V <sub>GS</sub> = 0V	-	-	1.5	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> = 9A, V <sub>GS</sub> = 0V	-	845	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	d <sub>i</sub> /d <sub>t</sub> = 100A/μs	-	8	-	μC

Notes:

- The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
- The E<sub>AS</sub> data shows Max. rating. The test condition is V<sub>DD</sub> = 100V, V<sub>GS</sub> = 10V, L = 50mH
- Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

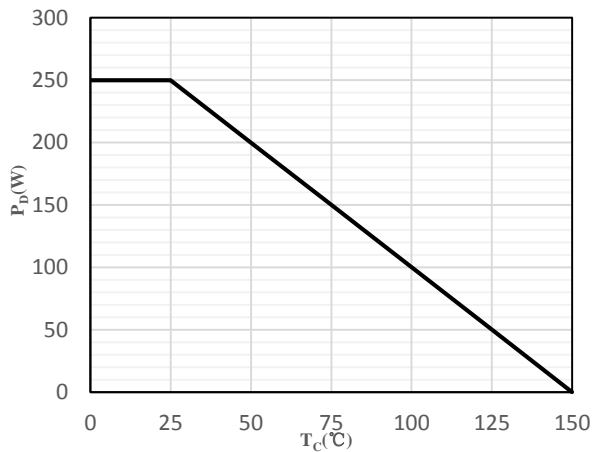


Fig 1 Power Dissipation

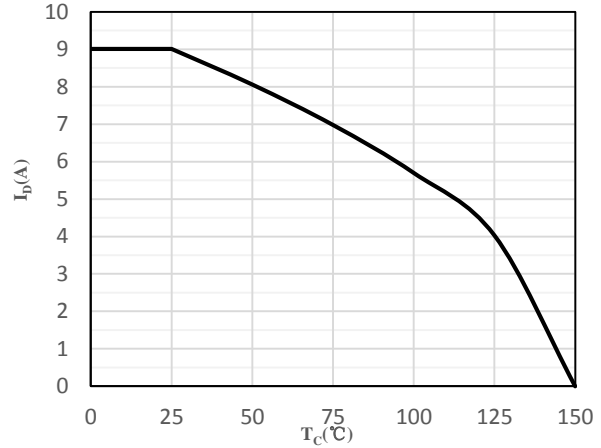


Fig 2 Drain Current

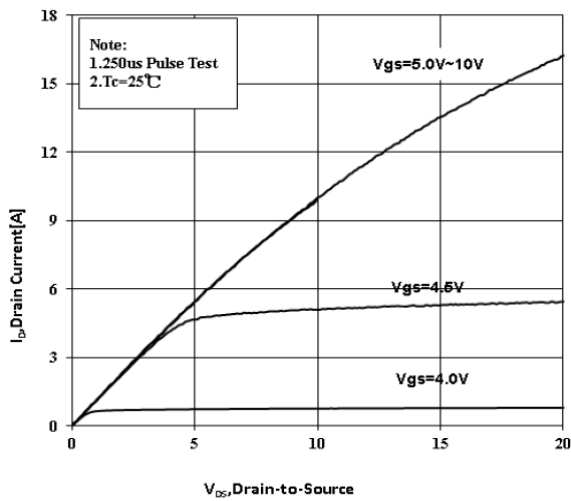


Fig 3 Typical Output Characteristics

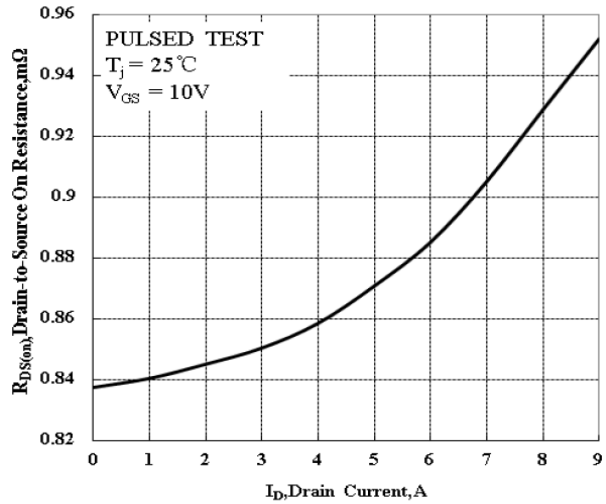


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

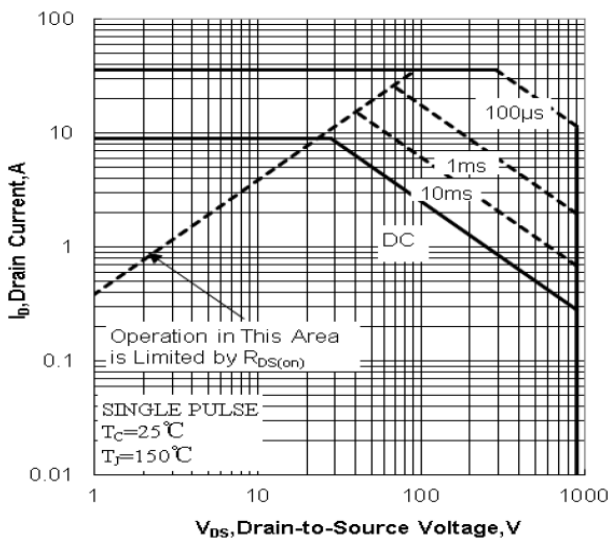


Fig 5 Safe Operation Area

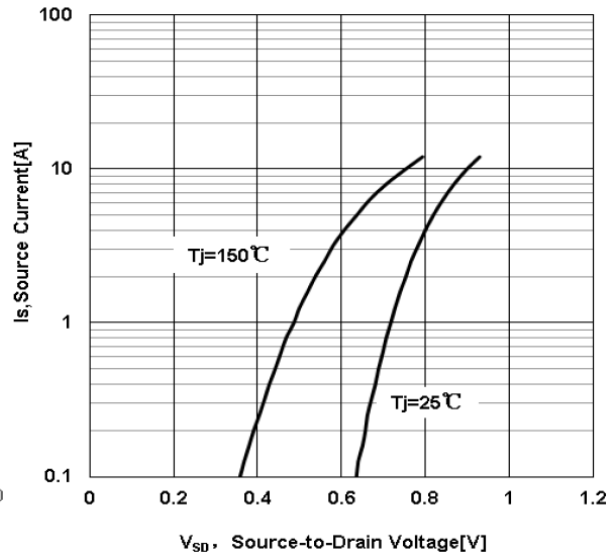


Fig 6 Body-Diode Characteristics

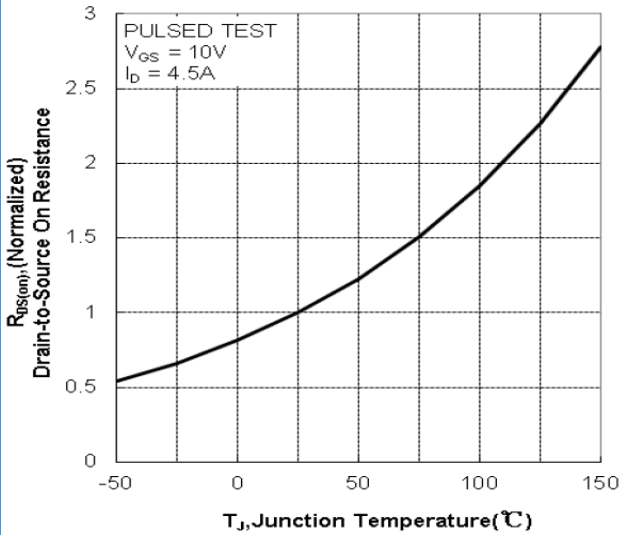


Fig 7 Normalized On-Resistance vs. Junction

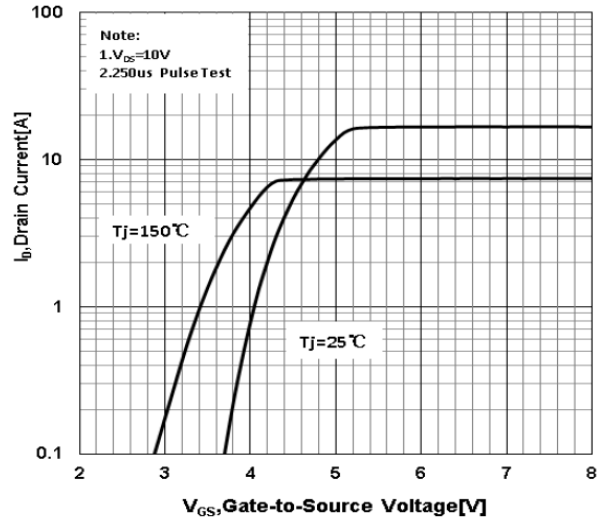


Fig 8 Transfer Characteristics

Temperature

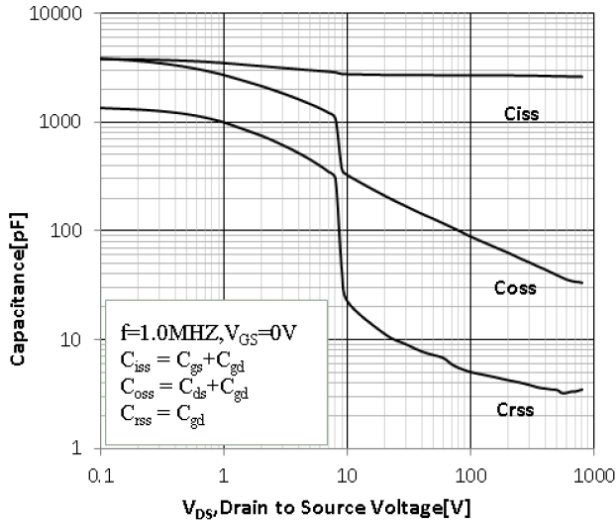


Fig 9 Capacitance Characteristics

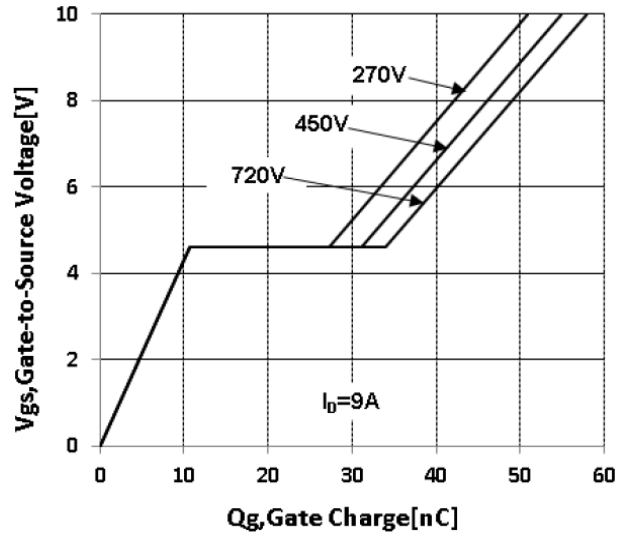


Fig 10 Gate-Charge Characteristics

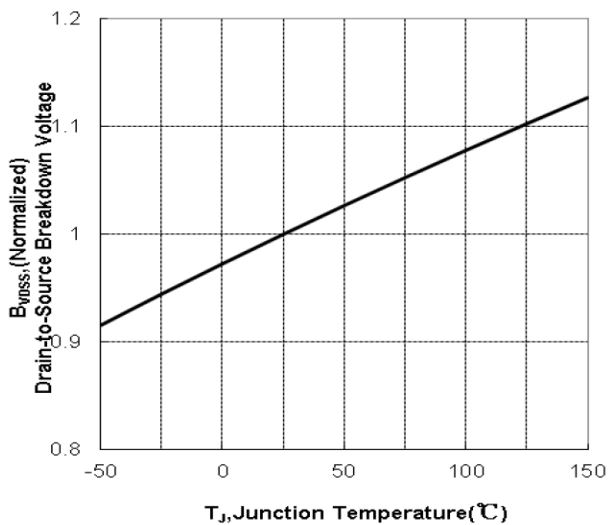


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

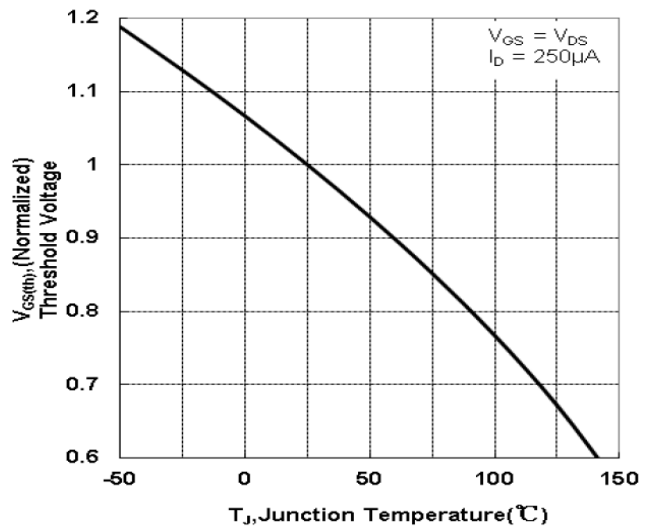
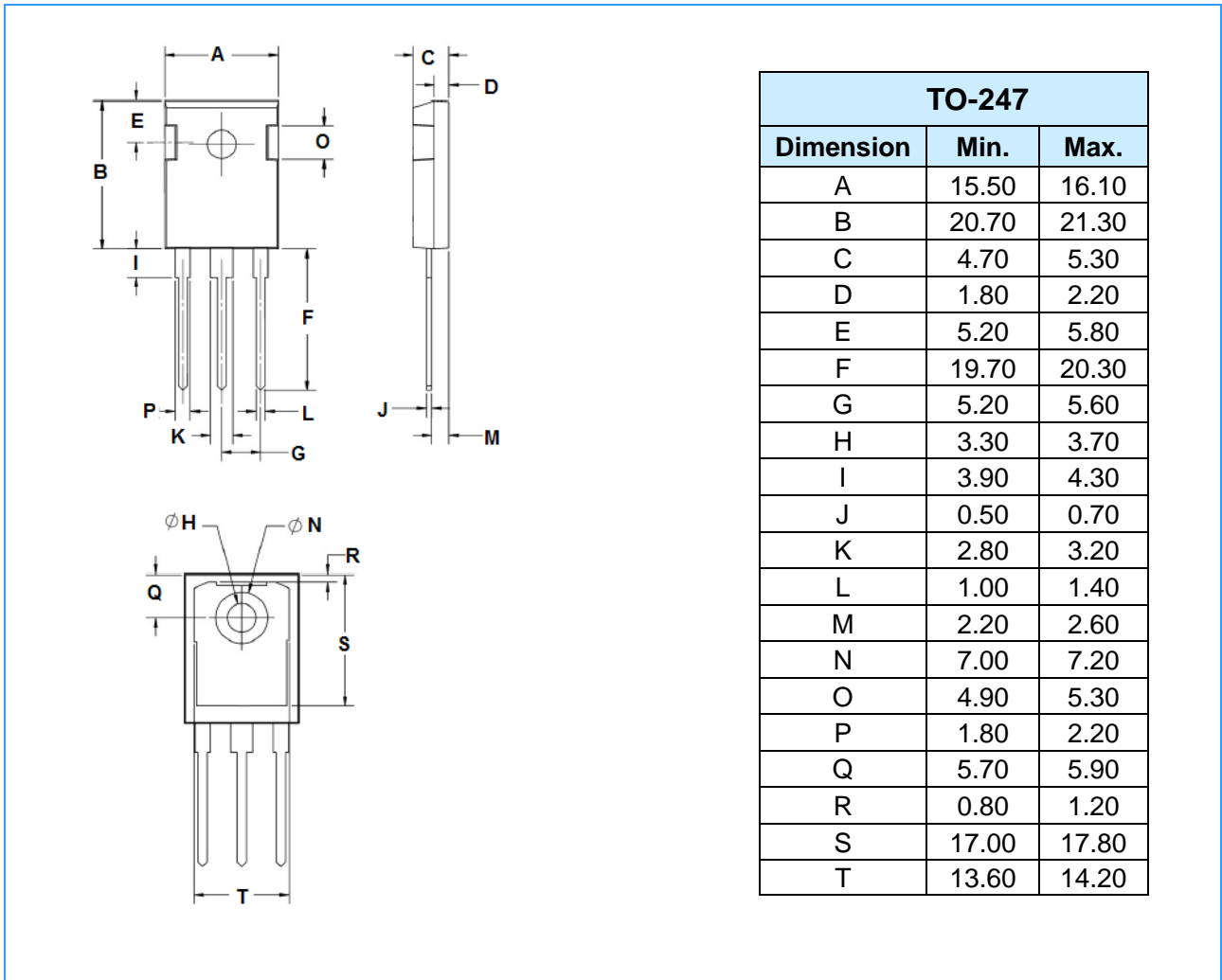


Fig 12 Normalized  $V_{GS(th)}$  vs. Junction Temperature

**Package Outline Dimensions** (Unit: mm)



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